## <u>Application for Scholarship Bond Deferment or Transfer</u>

	nolarship Check ☑ the box (as appropriate)  NUS Science & Technology Undergraduate Scholarship ☐ 5	Sembcorp Undergraduate Schola	rship		
☐ SIA-NOL Undergraduate Scholarship ☐ Undergraduate Scholarship for PRC Studen					
Bri	dging Period Check ☑ the box (as appropriate) NA   □ 20 Months ☑ 12 Months	☐ 7 Months			
Na	me:Xiang Shang Matric/Si	tudent NoA0133890A			
Dea	ar scholar,				
pos org at l	on graduation, you are required to serve your bond in a Singa tgraduate studies, overseas work, overseas training or othe anisation that awarded you a bonded scholarship or training east 3 months in advance.  ore you apply, please find out the amount of Banker's Guarar	r reasons, or transfer your bond g award, you need to fill in this a	to a Singapore pplication form		
	ase proceed to apply for deferment of tuition grant bond ained approval for the deferment of your scholarship bond.	at https://tgonline.moe.gov.sg	<b>after</b> you have		
	ase fill in the application form by <b>typing</b> , and attach the follow	ving supporting documents:			
A.	Bond Deferment for Postgraduate Studies	Che	eck ☑ the box		
Sup	porting Documents		appropriate)		
1.	Colour copy of passport and one of the following: (a) NRIC Work Pass	;, (b) Student Pass or (c)	<b></b> ✓		
2.	Letter of admission for postgraduate course		$\square$		
3.	Letter of offer of bonded postgraduate scholarship from a (if any)	Singapore organisation			
4.	All current and past employment records (if any)		$\square$		
В.	Bond Deferment for Overseas Work or Training				
			eck ☑ the box		
	porting Documents		appropriate)		
1.	Colour copy of passport and one of the following: (a) NRIC Work Pass	., (b) Student Pass or (c)			
2.	Letter of offer of overseas work or training				
3.	Letter from HR or company director to show either (if any	):			
	(a) Employer is a Singapore-based company* and (1) reason and end date of posting, (3) country posted to, (4) its overseas office and (5) percentage of ownership of the more than 50%; or	sons for posting, (2) start relationship with the			
	(b) HR letter to show that payroll and tax status remains continues to be tax liable in Singapore	unchanged, i.e. scholar			
4. *wi	All current and past employment records (if any) th global or regional HQ in Singapore				
C.	Bond Transfer				
<b>.</b> .	Tella Hallatoi		Check ☑ the		
Sun	porting Documents		box (as appropriate)		
յսր 1.					
2. Letter of offer of bonded scholarship or training award					
3.	All current and past employment records (if any)				
	ID IPA RG/SA/VA	(D) RG/SA/VA/VI Signed	BC placed		

LD	IPA	BG/SA/VA (P)	BG/SA/VA (V)	Signed	BG placed

1. Particulars of Applicant						
Name as in NRIC/Passport (include name in Chinese characters, if applicable)						
Xiang Shang 向尚						
FIN/NRIC		Matriculation No.	Admission Year		Graduat	ion Year
S9677458C		A0133890A	2014		2018	
Name of Course	e/Title of Degree	(if graduated)		1		
Bachelor of Scie	ence with Honou	rs (Merit) in Applied Mathematic	S			
Contact Address	(Cinganara)		Contact Address in Home Co	untru		
Contact Addres	s (Singapore)		Contact Address in Home Country (state in Chinese characters, if applicable)			
461 Clementi A	venue 3 #23-612					
Singapore, 1204	161		Wuhan Rongqiaojinjiang 8-1-4102, China Hubei 430034.			
			   湖北省武汉市硚口区融侨锦江 8-1-4102, 430034			
			MAN DEPENDENT OF THE PARTY OF	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	,	
Contact No. (Sir +65 90371449	ngapore)		Contact No. (Home Country +86 13871238696	)		
+03 903/1449			+80 13871238030			
Email Address(e	es)					
Xiangshang4@	gmail.com					
2. Employn	nent History	After Graduation (attach e	malovment records if a	lva	and the same	V. 1. 1. 1. 1. 1. 1. 1. 1. 1. 1. 1. 1. 1.
Start Date	End Date	Name of Employer	improvincine records, ir a	my/		Country of
(Month/Year)	(Month/Year)					Employment
Jan/2019	July/2021	Mizuho Bank ltd. Singap			Singapore	
		Bond Deferment (if any)		public field	I PION IN	
First Deferment	: raduate Studies		Second Deferment  D Postgraduate Studies			
	eas Work or Trai	ining	Overseas Work or Training			
	s (please specify	-	☐ Others (please spe	ecify)		
Start Date of 1s	t deferment	End Date of 1st deferment	Start Date of 2nd deferment		End Date	of 2nd
					deferme	nt
4. Application						
I am applying for  Bond Deferment for Postgraduate Studies (go to part 4a)						
☐ Bond Deferment for Other Reasons (go to part 4c)						
Bond Transfer (go to part 4d)  An Bond Deferment for Postgraduate Studies						
4a.Bond Deferment for Postgraduate StudiesName of InstitutionCountry of Institution		Faculty/School	Course (in	dicate if M	lasters/PhD)	
University of California, Los United States		Anderson Management			Ingineering	
Angeles		school			_	
Charle Date Office Cl. 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1						
Start Date End Date		Offer of bonded scholarship ☑ Nil □ A*STAR □ Others(please specify)				
Sept 13 <sup>th</sup> 2021 Dec 09 2022		(F				

Date leaving Singapore (applicable if doing postgraduate studies overseas) Sept 10 <sup>th</sup> 2021				
Plans after completion of postgraduate studies  After my postgraduate studies, I will:  Do postdoctoral work in Singapore to serve my bond Do other work in Singapore to serve my bond Others (please specify)				
4b. Bond Deferment	t for Overseas Work or Tra	aining		
I am applying for  Overseas	Work Overseas Training			
Name of Employer	Country of Work or Training	Address of Work or Training		
Start Date		End Date		
Date leaving Singapore				
Plans after overseas work or training (please specify)				
4c. Bond Deferment	t for Other Reasons			
Reason for Deferment (please	specify and attach all supporting	g documents)		
Address during Deferment (i.e. where you will be)				
Start Date		End Date		
Plans after bond deferment (please specify)				
4d. Bond Transfer				
I am applying to transfer my be ☐ bonded scholarship ☐ tra	ond to a Singapore organisation	that awarded me a		
Name of Singapore organisation		Name of bonded scholarship of	or training award	
☐ A*STAR		·	_	
Others (please specif	iy)			
Name of Officer in Charge		Start Date of course	End Date of course	
Contact Number of Officer in C	:harge	Email Address of Officer in Cha	arge	
5. Updated Particulars of Existing Sureties for Undergraduate Scholarship Agreement				
Name of Surety 1 Name of Surety 2				
Qu Zhihua		Xiang Kejian		
Wuhan Rongqiaojinjiang 8-1-4 湖北省武汉市硚口区融侨锦泊	Surety 2's Home Address (include address in <u>Chinese characters</u> , if applicable) wigqiaojinjiang 8-1-4102, China Hubei 430034. 没市硚口区融侨锦江 8-1-4102, 430034			
Surety 1's Contact No. +86 13607167372		Surety 2's Contact No. +8613886026386		
Surety 1's Email Address		Surety 2's Email Address		

1991894558@qq.com	xiangkejian@dpca.com.cn			
6. Any Other Information				
Any other relevant information that should be considered by t	he Sponsor in your application			
7. Declaration and Consent				
a. For applications under part 4a to 4c, should my bond deferment be approved, I agree and undertake to place a Banker's Guarantee in full within 1 month from the approval date of bond deferment and sign a Supplemental Agreement before the start of my bond deferment.				
b. I declare that I have notified my sureties of this application.				
knowledge and belief, and that I have not wilfully suppress	iven in this application are true and correct to the best of my sed any material fact. If any of the information given by me in tion may be rejected, my scholarship may be terminated and I			
d. I consent to the collection, use and disclosure of this inform	ation according to the Personal Data Protection Act.			

23/07/2024

Date

Signature of Applicant